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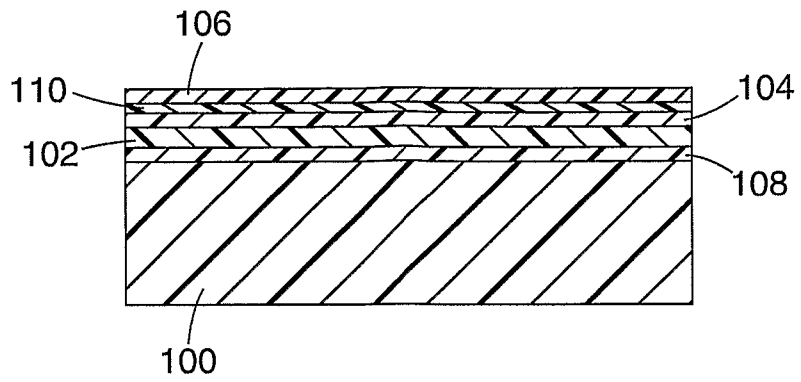
(54) Title: RADIATION CURABLE THERMAL TRANSFER ELEMENTS



(57) Abstract: Radiation curable thermal transfer elements including a substrate and a light-to-heat conversion layer overlaying the substrate, and processes to make the thermal transfer elements. The light-to-heat conversion layer is derived from a radiation curable material capable of being cured by exposure to radiation at a curing wavelength and an imaging radiation absorber material not substantially increasing radiation absorbance at the curing wavelength. The radiation curable transfer elements can be used in processes for making organic microelectronic devices.

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